

**What is claim d is:**

1. A substrate assembly for a gas discharge panel,  
comprising a dielectric layer and a protective layer of MgO  
being formed in this order on a substrate having electrodes,  
5 wherein the dielectric layer is a laminate of an organic  
dielectric layer and an inorganic dielectric layer in this order  
from a side of the substrate.
2. The substrate assembly for a gas discharge panel of  
10 claim 1, wherein the organic dielectric layer is made of a  
material selected from polyimide, polyamide imide,  
polysiloxane and polysilazane.
3. The substrate assembly for a gas discharge panel of  
15 claim 2, wherein the organic dielectric layer is made of a  
material selected from polysiloxane and polysilazane each  
having a side chain selected from alkyl, alkoxy and aryl.
4. The substrate assembly for a gas discharge panel of  
20 claim 1, wherein the inorganic dielectric layer is made of a  
material selected from a group consisting of SiO<sub>2</sub>, Al<sub>2</sub>O<sub>3</sub>, TiO<sub>2</sub>,  
ZrO<sub>2</sub>, AlN, Si<sub>3</sub>N<sub>4</sub> and SiC, and a mixture of two or more thereof.
5. The substrate assembly for a gas discharge panel of  
25 claim 1, wherein the inorganic dielectric layer is made of a

metal oxide having a smaller bond distance between an oxygen atom and a metal atom than the wavelength of an atom vacuum ultra violet ray.

5 6. The substrate assembly for a gas discharge panel of claim 1, wherein the organic dielectric layer has a smaller dielectric constant than that of the inorganic dielectric layer.

7. The substrate assembly of claim 1, wherein the  
10 organic dielectric layer has a thickness of 5-20  $\mu$  m and the inorganic dielectric layer has a thickness of 0.5-2  $\mu$  m.

8. The substrate assembly of claim 1, wherein the protective layer has a thickness of 0.5-1.5  $\mu$  m.

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9. A process for manufacturing a substrate assembly for a gas discharge panel, comprising:

forming an organic dielectric layer on a substrate;

forming an inorganic dielectric layer on the organic  
20 dielectric layer by a sol-gel, a sputtering or a vapor deposition process;

forming an organic compound layer containing Mg on the inorganic dielectric layer; and

firing the organic compound layer to form a protective  
25 layer of MgO.

10. A gas discharge panel, comprising:

a substrate assembly as disclosed in claim 1 disposed on a front side of the panel as a front substrate assembly;

5 a rear substrate assembly facing the front substrate assembly; and

a discharge space formed between the front and rear substrate assemblies,

wherein the rear substrate assembly is provided with  
10 barrier ribs for defining the discharge space and phosphors, the barrier ribs being formed on a substrate having electrodes, the phosphors being formed on side walls of the barrier ribs and on the substrate defined by the barrier ribs.